

MOSFETs Silicon N-Channel MOS (DTMOSVI)

TK155E60Z1

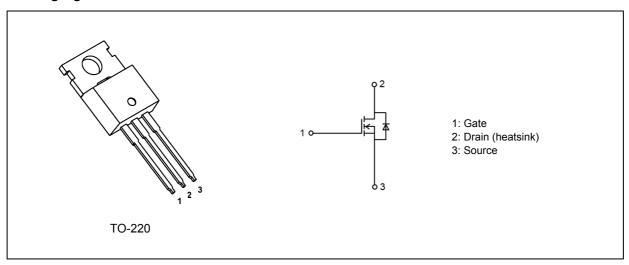
1. Applications

· Switching Power Supplies

2. Features

- (1) Low drain-source on-resistance: $R_{DS(ON)} = 0.13 \Omega$ (typ.)
- (2) High-speed switching properties with lower capacitance.
- (3) Enhancement mode: $V_{th} = 3$ to $4 \text{ V} (V_{DS} = 10 \text{ V}, I_D = 0.61 \text{ mA})$

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (T_a = 25 °C unless otherwise specified)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	600	V
Gate-source voltage		V _{GSS}	±30	
Drain current (DC)	(Note 1)	I _D	17	Α
Drain current (pulsed)	(Note 1)	I _{DP}	68]
Power dissipation (T _c = 25 °C)		P _D	130	W
Single-pulse avalanche energy	(Note 2)	E _{AS}	163	mJ
Single-pulse avalanche current		I _{AS}	3.8	Α
Reverse drain current (DC)	(Note 1)	I _{DR}	17]
Reverse drain current (pulsed)	(Note 1)	I _{DRP}	68]
Channel temperature		T _{ch}	150	°C
Storage temperature		T _{stg}	-55 to 150]
Mounting torque		TOR	0.6	N · m

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

1

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production

2024-12

Rev.1.0



5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal resistance	R _{th(ch-c)}	0.961	°C/W
Channel-to-ambient thermal resistance	R _{th(ch-a)}	83.3	

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: V_{DD} = 90 V, T_{ch} = 25 °C (initial), L = 20 mH, I_{AS} =3.8 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μΑ
Drain cut-off current	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	2	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 0.61 mA	3	_	4	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 10 V, I _D = 5.4 A		0.13	0.155	Ω

6.2. Dynamic Characteristics (Ta = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 300 V, V _{GS} = 0 V, f = 100	_	1350	_	pF
Reverse transfer capacitance	C _{rss}	kHz	_	1.7	_	
Output capacitance	Coss		_	35	_	
Effective output capacitance (Note (energy related)	3) C _{o(er)}	V _{DS} = 0 to 400 V, V _{GS} = 0 V	_	60		
Effective output capacitance (Note (time related)	4) C _{o(tr)}		_	410	_	
Gate resistance	r _g	V _{DS} = OPEN , f = 1 MHz	_	3.4	_	Ω
Switching time (rise time)	t _r	See Figure 6.2.1	_	20	_	ns
Switching time (turn-on time)	t _{on}		_	40	_	
Switching time (fall time)	t _f]	_	5	_	
Switching time (turn-off time)	t _{off}		_	70	_	
MOSFET dv/dt ruggedness	dv/dt	$V_{DS} \leq V_{DSS}, \ I_D \leq 8.5 \ A$	70	_		V/ns

Note 3: $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0V to 400V. Note 4: $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0V to 400V.

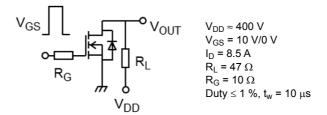


Fig. 6.2.1 Switching Time Test Circuit



6.3. Gate Charge Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 17 \text{ A}$	_	24		nC
Gate-source charge 1	Q _{gs1}			7.7		
Gate-drain charge	Q _{gd}		_	7	_	

6.4. Source-Drain Characteristics ($T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	V_{DSF}	I _{DR} = 17 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time		V _{DD} = 400 V,	_	270	_	ns
Reverse recovery charge	Q_{rr}	$I_{DR} = 8.5 \text{ A}, V_{GS} = 0 \text{ V}$ - $dI_{DR}/dt = 100 \text{ A/us}$	_	2.7	_	μС
Peak reverse recovery current	I _{rr}	-αιρκ/αι – 100 Α/μδ	_	20	_	Α
Diode dv/dt ruggedness	dv/dt	$V_{DD} \le 400 \text{ V}, I_{DR} \le 8.5 \text{ A}, V_{GS} = 0 \text{ V}$	40	_	_	V/ns

7. Marking

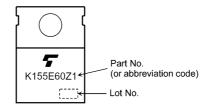


Fig. 7.1 Marking



8. Characteristics Curves (Note)

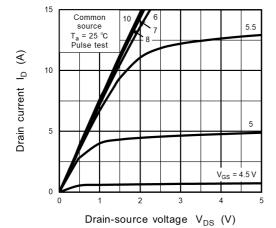


Fig. 8.1 I_D - V_{DS}

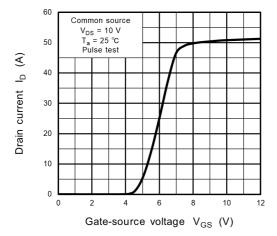


Fig. 8.3 I_D - V_{GS}

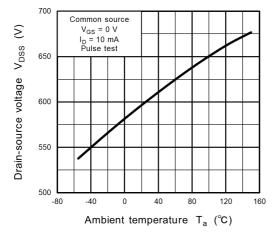


Fig. 8.5 V_{DSS} - T_a

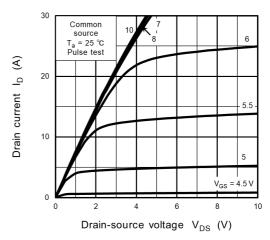


Fig. 8.2 I_D - V_{DS}

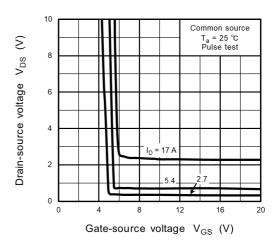


Fig. 8.4 V_{DS} - V_{GS}

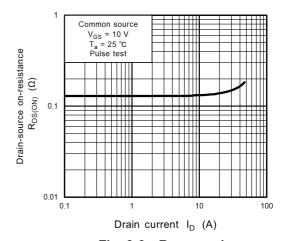
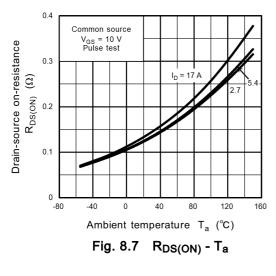


Fig. 8.6 R_{DS(ON)} - I_D





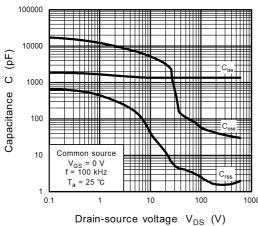


Fig. 8.9 C - V_{DS}

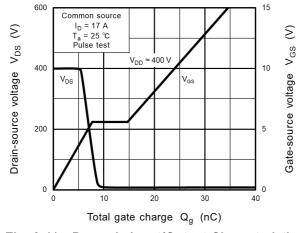


Fig. 8.11 Dynamic Input/Output Characteristics

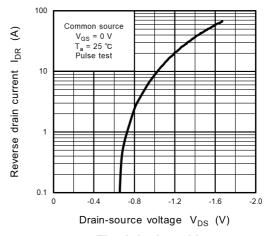


Fig. 8.8 I_{DR} - V_{DS}

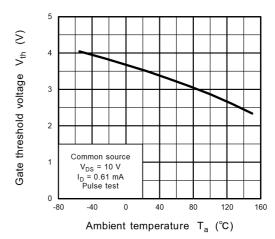


Fig. 8.10 V_{th} - T_a

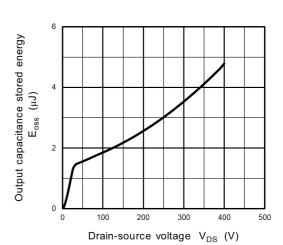


Fig. 8.12 E_{OSS} - V_{DS}



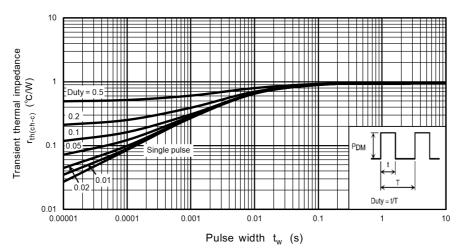


Fig. 8.13 r_{th} - t_w (Guaranteed Maximum)

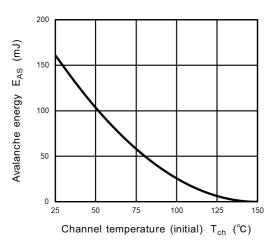
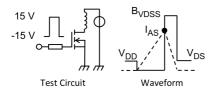


Fig. 8.14 E_{AS} - T_{ch} (Guaranteed Maximum)



$$V_{DD} = 90 \text{ V, L} = 20 \text{ mH} \qquad E_{AS} = \frac{1}{2} \cdot \text{L} \cdot \text{I}_{AS}^2 \cdot \left(\frac{\text{B}_{VDSS}}{\text{B}_{VDSS} - \text{V}_{DD}} \right)$$

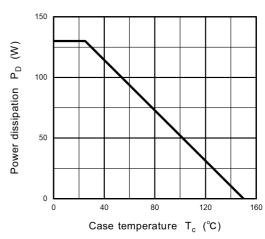


Fig. 8.15 P_D - T_c (Guaranteed Maximum)

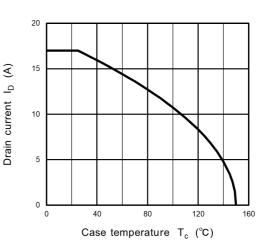


Fig. 8.17 $I_D - T_c$ (Guaranteed Maximum)

Fig. 8.16 Test Circuit/Waveform



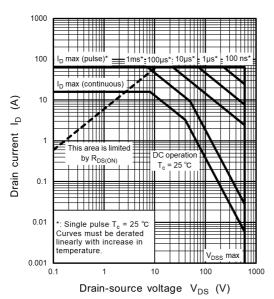


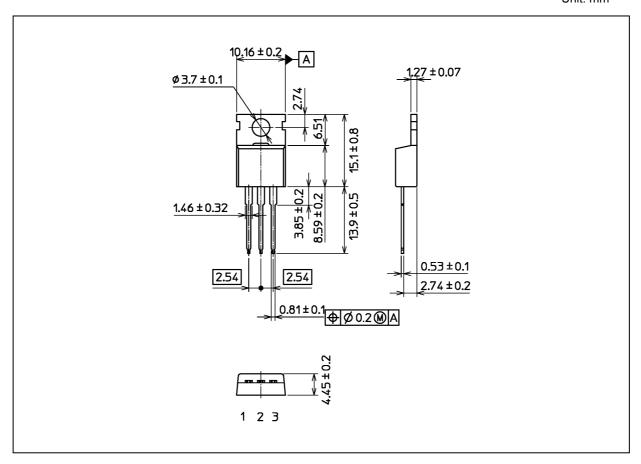
Fig. 8.18 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



Weight: 1.93 g (typ.)

	Package Name(s)
TOSHIBA: 2-10X1A	
Nickname: TO-220	



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